

AA2214VRBXS/A-TR-AMT

2.2 x 1.4 mm Surface Mount LED Lamp



DESCRIPTIONS

- The source color devices are made with InGaN Light Emitting Diode
- · Electrostatic discharge and power surge could damage the LEDs
- It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- · All devices, equipments and machineries must be electrically grounded

FEATURES

- 2.2 mm x 1.4 mm, 1.3 mm high
- Low power consumption
- · Available on tape and reel
- Package: 2000 pcs / reel
- Moisture sensitivity level: 3
- RoHS compliant

APPLICATIONS

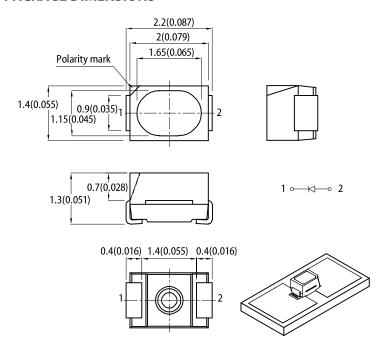
- Traffic signaling
- · Backlighting (illuminated advertising, general lighting)
- · Interior and exterior automotive lighting
- · Substitution of micro incandescent lamps
- Reading lamps
- Signal and symbol luminaire for orientation
- Marker lights (e.g. Steps, exit ways, etc)
- · Decorative and entertainment lighting
- Indoor and outdoor commercial and residential architectural lighting

ATTENTION

Observe precautions for handling electrostatic discharge sensitive devices

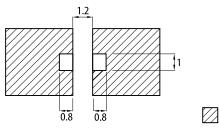


PACKAGE DIMENSIONS



RECOMMENDED SOLDERING PATTERN

(units: mm; tolerance: \pm 0.1)



Solder Resist

- 1. All dimensions are in millimeters (inches).
- Tolerance is ±0.2(0.008") unless otherwise noted.
 The specifications, characteristics and technical data described in the datasheet are subject to
- change without prior notice.

 The device has a single mounting surface. The device must be mounted according to the specifications.

SELECTION GUIDE

Dord November	Emitting Color	Iv (mcd) @ 20mA [2] View			Viewing Angle [1]
Part Number	(Material)	Code.	Min.	Max.	201/2
AA2214VRBXS/A-TR-AMT		Т	700	1000	
	■ Blue (InGaN)	U	1000	1300	120°
		V	1300	1600	

Notes.

1. 61/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity / luminous flux: +/-15%.

3. Luminous intensity value is traceable to CIE127-2007 standards.



ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Dovementor	Symphol	Emitting Color	Value		l l m i 4	
Parameter	Symbol	Emitting Color	Тур.	Max.	Unit	
Chromaticity Coordinates x I _F = 20mA	x ^[1]	Blue	0.19	-	-	
Chromaticity Coordinates y I _F = 20mA	y ^[1]	Blue	0.26	-	-	
Capacitance	С	Blue	100	-	pF	
Forward Voltage I _F = 20mA	V _F ^[2]	Blue	3.3	4.0	V	
Reverse Current (V _R = 5V)	I _R	Blue	-	50	uA	
Temperature Coefficient of x $I_F = 20mA$, $-10^{\circ}C \le T \le 100^{\circ}C$	TC _x	Blue	-0.16	-	10 ⁻³ /°C	
Temperature Coefficient of y I_F = 20mA, -10°C \leq T \leq 100°C	TC _y	Blue	-0.18	-	10 ⁻³ /°C	
Temperature Coefficient of V_F I_F = 20mA, -10°C \leq T \leq 100°C	TC _V	Blue	-3.0	-	mV/°C	

ABSOLUTE MAXIMUM RATINGS at $T_A=25$ °C

Parameter	Symbol	Value	Unit
Power Dissipation	P _D	120	mW
Reverse Voltage	V _R	5	V
Junction Temperature	T _j	115	°C
Operating Temperature	T _{op}	-40 to +100	°C
Storage Temperature	T _{stg}	-40 to +110	°C
DC Forward Current	I _F	30	mA
Peak Forward Current	I _{FM} ^[1]	100	mA
Electrostatic Discharge Threshold (HBM)	-	250	V
Thermal Resistance (Junction / Ambient)	R _{th JA} [2]	330	°C/W
Thermal Resistance (Junction / Solder point)	R _{th JS} ^[2]	215	°C/W

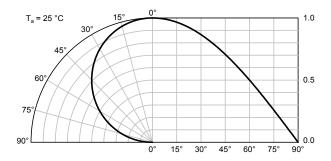
^{1.} Measurement tolerance of the chromaticity coordinates is ±0.01.
2. Forward voltage: ±0.1V.
3. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

Notes:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. $R_{lh, M}$, $R_{lh, M}$, $R_{lh, M}$ Results from mounting on PC board FR4 (pad size \geq 16 mm² per pad).
3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

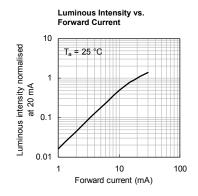


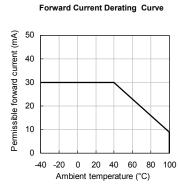
TECHNICAL DATA

SPATIAL DISTRIBUTION

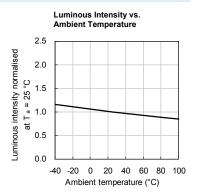


Forward Current vs. Forward Voltage 100 T_a = 25 °C Forward current (mA) 10 2.0 2.8 3.2 3.6 Forward voltage (V)

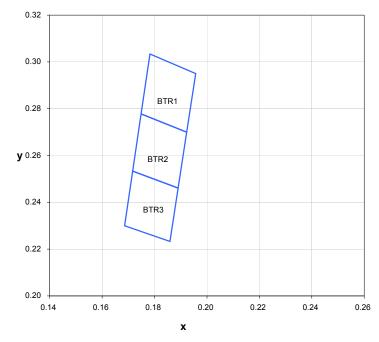




BLUE



CIE CHROMATICITY DIAGRAM



	Х	у
	0.1782	0.3034
BTR1	0.1749	0.2778
BIKI	0.1923	0.2700
	0.1957	0.2950
	0.1749	0.2778
BTR2	0.1716	0.2533
BIRZ	0.1890	0.2461
	0.1923	0.2700
BTR3	0.1716	0.2533
	0.1686	0.2300
	0.1859	0.2233
	0.1890	0.2461

Notes. Shipment may contain more than one chromaticity regions. Orders for single chromaticity region are generally not accepted. Measurement tolerance of the chromaticity coordinates is ±0.01.



REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS

300 above 255°C (°C) 260°C max. 30s max. 10s max. 250 3°C/s max. 6°C/s max. 200 150 Temperature pre-heating 100 150~200°C above 217°C 60~120s 50 25°C 0 50 100 150 200 250 300 (sec Time

Notes:

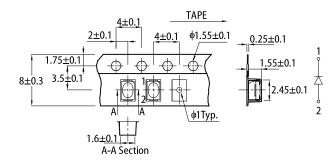
- Notes.

 1. Don't cause stress to the LEDs while it is exposed to high temperature.

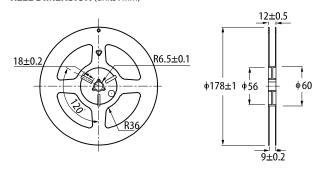
 2. The maximum number of reflow soldering passes is 2 times.

 3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

TAPE SPECIFICATIONS (units: mm)



REEL DIMENSION (units: mm)



HANDLING PRECAUTIONS

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

2. Do not directly touch or handle the silicone lens

surface. It may damage the internal circuitry.

- 1. Handle the component along the side surfaces by using forceps or appropriate tools.

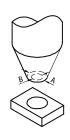
- 3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.







- 4-1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4-2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4-3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.
- 5. As silicone encapsulation is permeable to gases, some corrosive substances such as H₂S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.





RELIABILITY TEST ITEMS AND CONDITIONS

The reliability of products shall be satisfied with items listed below

LOT TOLERANCE PERCENT DEFECTIVE (LTPD): 10%

No.	Test Item	Standards	Test Condition	Test Times / Cycles	Number of Damaged
1	Continuous operating test	-	T _a = 25°C, I _F = maximum rated current *	1,000 h	0 / 22
2	High Temp. operating test	EIAJ ED-4701/100(101)	$T_a = 100$ °C, $I_F = derated current at 100°C 1,0$		0 / 22
3	Low Temp. operating test	-	$T_a = -40$ °C, $I_F = \text{maximum rated current *}$		0 / 22
4	High temp. storage test	EIAJ ED-4701/100(201)	T _a = maximum rated storage temperature	1,000 h	0 / 22
5	Low temp. storage test	EIAJ ED-4701/100(202)	T _a = -40°C	1,000 h	0 / 22
6	High temp. & humidity storage test	-	T _a = 60°C, RH = 90%	500 h	0 / 22
7	High temp. & humidity operating test	-	T_a = 60°C, RH = 90% I_F = derated current at 60°C	500 h	0 / 22
8	Soldering reliability test	EIAJ ED-4701/100(301)	Moisture soak: 30°C, 70% RH, 72h Preheat: 150~180°C (120s max.) Soldering temp: 260°C(10s)	2 times	0 / 18
9	Thermal shock operating test	-	$T_a = -40$ °C(15min) ~ 100°C(15min) I_F = derated current at 100°C	1,000 cycles	0 / 22
10	Thermal shock test	-	$T_a = -40$ °C(15min) ~ 100°C(15min)	1,000 cycles	0 / 22
11	Electric Static Discharge (ESD)	EIAJ ED-4701/100(304)	C = 100pF, R2 = 1.5KΩ V = 250V Once each Polarity		0 / 22
12	Vibration test	-	a = 196m/s², f = 100~2KHz, t = 48min for all xyz axes 4 times		0 / 22

^{*:} Refer to forward current vs. derating curve diagram

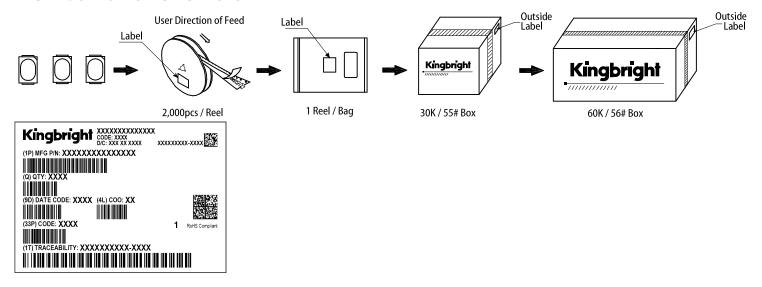
CRITERIA FOR JUDGING DAMAGE

Items	Symbols	Conditions	Failure Criteria	
luminous Intensity	I _V	I _F = 20mA	Testing Min. Value < Spec. Min. Value x 0.5	
Forward Voltage	V _F	I _F = 20mA	Testing Max. Value ≥ Spec. Max. Value x 1.2	
Reverse Current	I _R	V _R = Maximum Rated Reverse Voltage	Testing Max. Value ≥ Spec. Max. Value x 2.5	
High temp. storage test	-	-	Occurrence of notable decoloration, deformation and cracking	





PACKING & LABEL SPECIFICATIONS



PRECAUTIONARY NOTES

- The information included in this document reflects representative usage scenarios and is intended for technical reference only.

 The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.

 The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening
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